

IN THE SPECIFICATION

Please replace the paragraph that spans pages 3 and 4 (from page 3, line 27 to page 4, line 2) as follows:

Since the Ag-epoxy adhesive is used to attach the semiconductor chip 12 to the base substrate 20, moisture enters the package due to the hygroscopicity of the Ag-epoxy. Further, an exhaust gas generated during the curing of the Ag-epoxy adhesive contaminates the mirrors 16 on the active surface of the semiconductor chip 12. Therefore, it is preferable to use solder as the adhesive means. However, with the use of solder, damage such as the burning of the first anti-sticking film or the deformation of the mirrors can occur. In other words, to attach the semiconductor chip to the base structure, the solder must be melted at a temperature of ~~150°C~~ 150°C or more. Such a high temperature causes the burning of the first anti-sticking film or the deformation of the mirrors 16 in the semiconductor in the semiconductor chip 12.

Please replace the first paragraph on page 8, lines 1-6 as follows:

If the adhesive 130 is used, the die-attaching step is carried out at higher temperature than if the AG-epoxy adhesive is used. For example, with the solder, the die attaching step is processed at a temperature of approximately ~~150°C~~ 150°C or more. However, since the mirrors 116 of the semiconductor chip are coated with the photoresist 113, although the die-attaching step is carried out at a high temperature, the mirrors 116 of the semiconductor chips are not damaged.